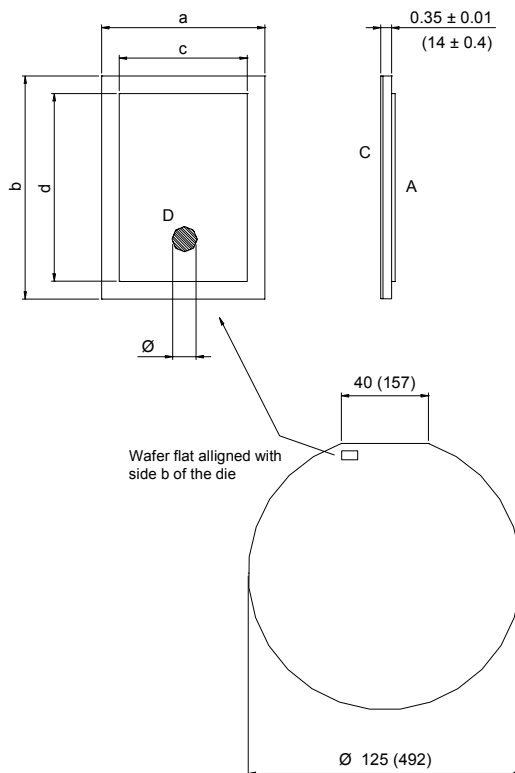


SCHOTTKY DIE 115 x 170 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (MILS).

2. CONTROLLING DIMENSION: (MILS).

3. DIMENSIONS AND TOLERANCES:

$a = 4.32 \pm 0, - 0.01$

(170 $\pm$ 0, - 0.4)

$b = 2.92 \pm 0, - 0.01$

(115 $\pm$ 0, - 0.4)

$c = 4.17 \pm 0, - 0.01$

(164 $\pm$ 0, - 0.4)

$d = 2.77 \pm 0, - 0.01$

(109 $\pm$ 0, - 0.4)

$\varnothing = 1 \pm 0.15$

(40 $\pm$ 6)

4. LETTER DESIGNATION:

A = Anode (Top Metal)

C = Cathode (Back Metal)

D = Reject Ink Dot (only on non-conforming dies)

5. SAWING:

Recommended Blade

SEMITEC S1025 QS00 Blade

Sawing Street

0.05 $\pm$ 0, - 0.005

(2 $\pm$ 0, - 0.2)

NOT TO SCALE

NOTE: 10 mils die thickness is available on specific request only.
Contact factory for information.

Electrical Characteristics

Device #	T _J Max. (°C)	V _R (V)	Typ. I _R @ 25°C (μA)	Typ. I _R @ 125°C (mA)	Max. V _F @ I _F (V)	Package Style
SC170 R 015x5x	125	15	5000	600	0.41 @ 19A	TO-220
SC170 S 020x5x	150	20	n.a. contact factory			
SC170 S 030x5x	150	30	350	140	0.48 @ 20A	TO-220
SC170 S 045x5x	150	45	250	100	0.57 @ 20A	TO-220
SC170 S 060x5x	150	60	140	70	0.61 @ 20A	TO-220
SC170 H 045x5x	175	45	40	14	0.60 @ 18A	TO-220
SC170 H 100x5x	175	100	15	8	0.80 @ 20A	TO-220
SC170 H 150x5x	175	150	n.a. contact factory			

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC170xxxx A 5x	Wire Bondable	—	Al 30 kÅ	—	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ
SC170xxxx S 5x	Solderable	Ti 2 kÅ	Ni 1 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

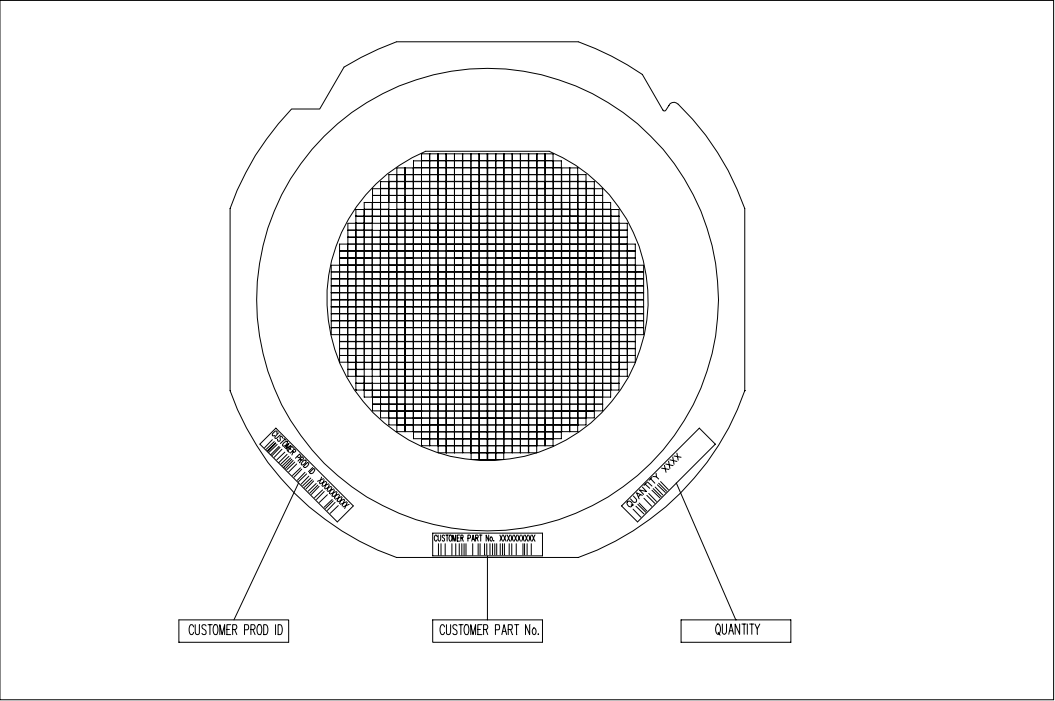
Device #	Description	Minimum Order Quantity Die in Sale Package
SC170xxxx B	Inked Probed Unsawn Wafer (Wafer in Box)	800
SC170xxxx R	Probed Die in Tape & Reel	n.a.
SC170xxxx P	Probed Die in Waffle Pack	800
SC170xxxx F	Inked Probed Sawn Wafer on Film	800

Ordering Information Table

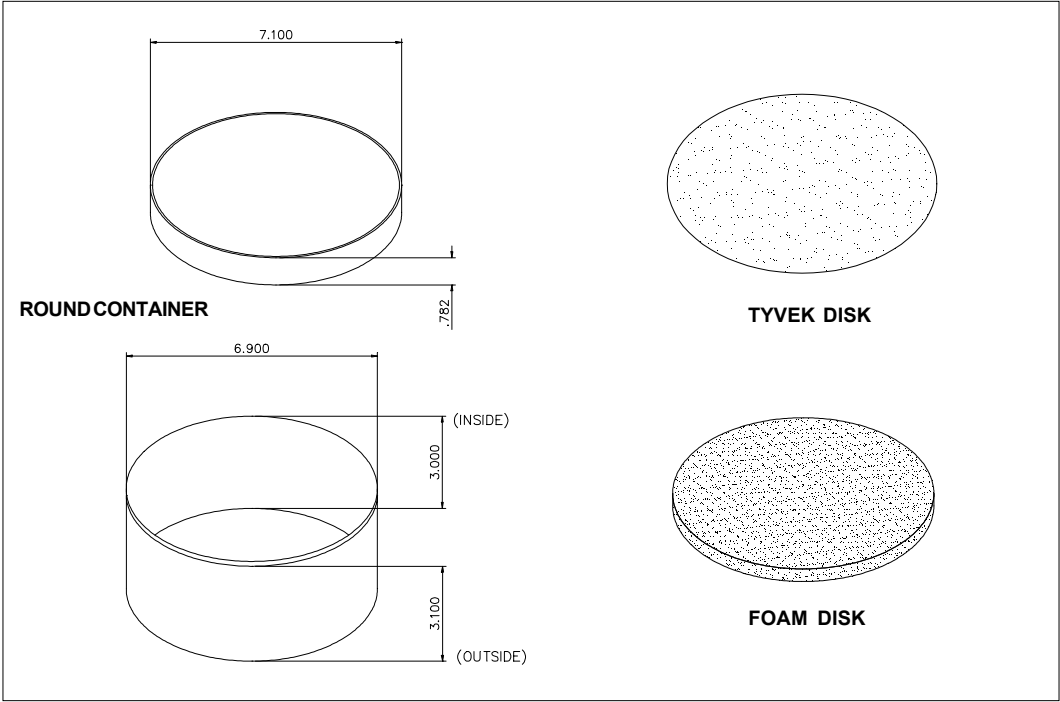
Device Code						
SC	170	H	100	S	5	B
1	2	3	4	5	6	7
1	- Schottky Die					
2	- Chip Dimension in Mils					
3	- Process (see Electrical Characteristics Table)					
4	- Voltage code: Code = V_{RRM}					
5	- Chip surface metallization (see Mechanical Data Table)					
6	- Wafer Diameter in inches					
7	- Packaging (see Packaging Table)					

H = 830 Process
R = OR'ing Process
S = Standard Process

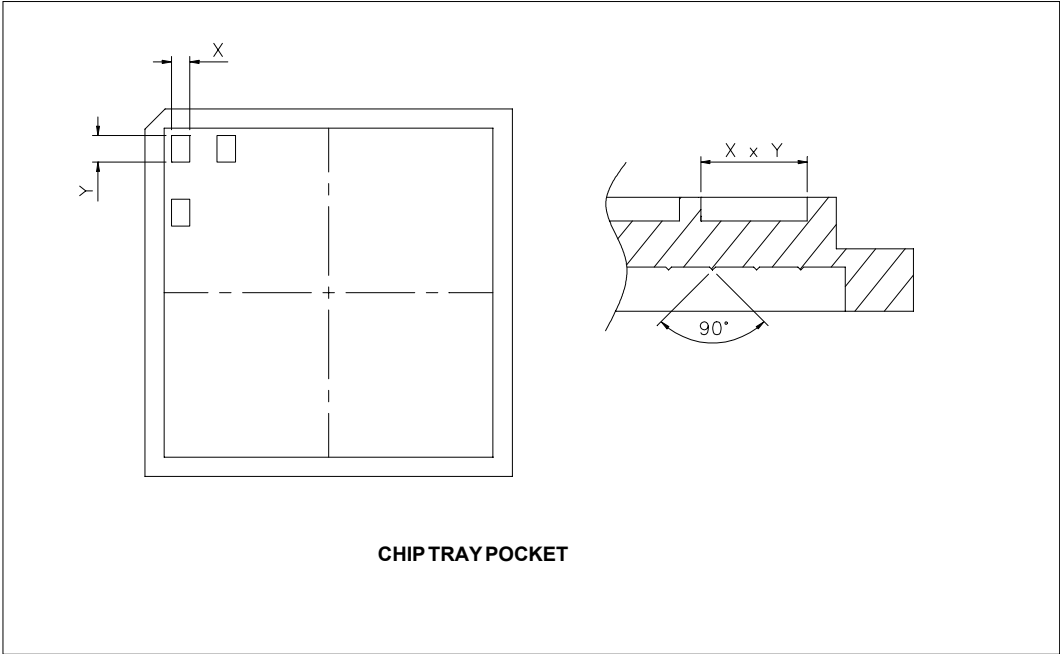
Wafer on Film



Wafer in Box



Die in Waffle Pack



Tape and Reel

